60×108MM YELLOW BACKLIGHT

A-TBL-62119UY12

Features

- ※ 60×108mm is emitting surface size of backlight
- X Low power requirement, solid state reliability.
- * Multicolor available, stackable horizontally.
- * Categorized for luminous intensity.
- * Easy mounting on P.C. boards.
- ※ Remain within RoHS compliant version.

Applications

- ※ General lighting solutions
- ※ LCD display backlight

Ordering Information

| Part | Part Emission Emission Number Size Color | Brightness IV (cd/m ²) | | | |
|-----------------|---|------------------------------------|------|------|------|
| Number | | Color | Min. | Тур. | Max. |
| A-TBL-62119UY12 | 60×108MM | Yellow | 100 | 200 | 300 |

A-TBL-62119UY12

Maximum Ratings

| Parameter | Symbol | Value | Unit |
|---|------------------|----------|------|
| Operating temperature | T _{OP} | -35 ~ 85 | °C |
| Storage temperature | T _{STG} | -35 ~ 85 | °C |
| Peak forward current ($T_A=25 \text{ °C}$) * ¹ | I _{PF} | 60 | mA |
| Reverse voltage (TA=25 °C) | V _R | 5 | V |
| Power consumption (TA=25 °C) | Р | 500 | mW |

*1 at 1/10 Duty Cycle

Electrical / Optical Characteristics (1)

 $(T_A = 25 \text{ °C \& IF} = 20 \text{ mA})$

| Parameter | | Symbol | Value | Unit |
|-----------------------------|--------|------------------------|-------|------|
| Wavelength at peak emission | (Typ.) | λ_{P} | 590 | nm |
| Spectral bandwidth at 50% | (Typ.) | Δλ | 20 | nm |
| | (Min.) | I _F | 40 | |
| Forward Current | (Typ.) | $I_{\rm F}$ | 45 | mA |
| | (Max.) | $I_{\rm F}$ | 50 | |
| | (Min.) | $V_{\rm F}$ | - | |
| Forward voltage | (Тур.) | $V_{\rm F}$ | 10 | V |
| | (Max.) | $V_{\rm F}$ | - | |
| Color temperature | (Min.) | ТС | - | K |
| | (Max.) | TC | - | Κ |
| Luminous Uniformity (Typ.) | | - | 80% | - |
| Discreteness | (Typ.) | - | 20% | - |

Luminous Intensity Bin Groups

 $(T_A = 25 \,^{\circ}C)$

| Brightness IV (cd/m ²) | | | | |
|------------------------------------|------|------|--|--|
| Min. | Тур. | Max. | | |
| 100 | 200 | 300 | | |

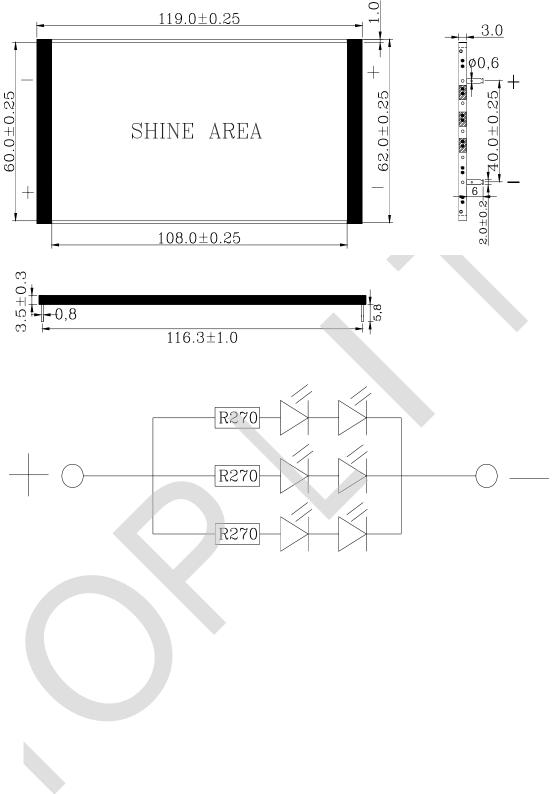
URL: www.topliteusa.com Email: sales@toplightusa.com



Yellow 2 Luminous 1 Relatibe Intensity 0 400 450 500 550 600 650 700 750 800 Wavelength(λ) nm Relative Intensity & wavelength FORWARD CURRENT VS RELATIVE INTENSITY VS FORWARD VOLTAGE FORWARD CURRENT 50 5.0 Luminous Intensity Relative Value at IF=20mA Current(mA) 4.0 40 30 3.0 20 2.0 Forward 15 10 1.0 5 0 0 1.2 1.6 0 10 20 30 50 2.0 2.4 2.8 3.0 40 Current(mA) IF-Forward Forward Voltage(V) FORWARD CURRENT VS DERATING CURVE LUMINOUS INTENSITY VS AMBIENT TEMPERATURE 50 Relative Luminous Intensity 2 Current(mA) 40 1 30 0. 20 0.2 Forward 10 0. 0 0 0 20 40 60 80 100 -30 $-10\ 0\ 10$ 30 50 70 Ambient Temperature Ta(°C) Ambient Temperature Ta(°C)



Package Outline Dimensions



Notes:

- 1. All dimensions are in millimeters. Tolerance is +/-0.25 unless otherwise noted.
- 2. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

URL: www.topliteusa.com Email: sales@toplightusa.com



Display Soldering Conditions

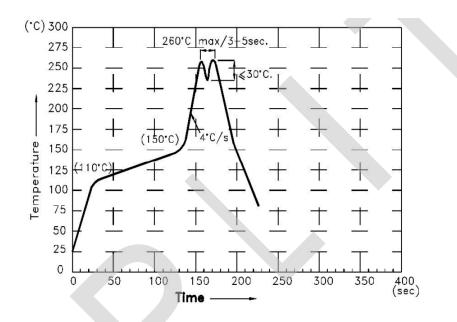
The recommended conditions for soldering are as follows. Because the component is made with epoxy resin, the units are susceptible to heat. Therefore, the preheating and soldering temperatures should be kept as low as possible to avoid damage.

1. Manual Soldering Conditions(with 1.5mm Iron tip)

Iron Tip Temperature: 350°C Max, Time: 3s Max Position: The iron should be situated at least 2mm away from the root of the leads.

2. Through the Wave Soldering Conditions

Wave Soldering Profile For Lead-free Through-hole LED



3. Soldering General Notes:

- a. TOPLITE recommend manual soldering to be used only for repair and rework purposes. The soldering iron should not exceed 30W in power. The tip of the soldering iron should not touch the reflector case to avoid heat-damage.
- b. Maintain the pre-heat and peak temperatures with dip units as low as possible and the times as short as is feasible, since the products are susceptible to heat during flow soldering.
- c. After soldering, allow at least three minutes for the component to cool to room temperature before further operations.
- d. If components will undergo multiple soldering processes, or other processes where the components may be subjected to intense heat, please check with TOPLITE for compatibility.